## 1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD882D leadless ultra small Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

### 2. Features and benefits

- Forward current: I<sub>F</sub> ≤ 0.2 A
- Reverse voltage: V<sub>R</sub> ≤ 40 V
- Low forward voltage: VF ≤ 600 mV
- Ultra small and leadless SMD plastic package
- Solderable side pads
- · Package height typ. 0.37 mm
- Qualified according to AEC-Q101 and recommended for use in automotive applications

### 3. Applications

- · Low voltage rectification
- · High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- · Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching

### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; $T_{amb} \le 120 ^{\circ}\text{C}$	[1]	-	-	0.2	Α
		$\delta$ = 0.5; f = 20 kHz; square wave; T <sub>sp</sub> ≤ 140 °C		-	-	0.2	Α
I <sub>R</sub>	reverse current	V <sub>R</sub> = 25 V; T <sub>amb</sub> = 25 °C		-	0.3	0.5	μΑ
$V_R$	reverse voltage			-	-	40	V
V <sub>F</sub>	forward voltage	$I_F$ = 200 mA; $t_p \le 300 \mu s$ ; $\delta \le 0.02$ ; $T_{amb}$ = 25 °C		-	540	600	mV

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.



# 5. Pinning information

#### **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]		
2	A	anode	Transparent top view  DFN1006D-2 (SOD882D)	K <del>     </del> A sym001

[1] The marking bar indicates the cathode.

## 6. Ordering information

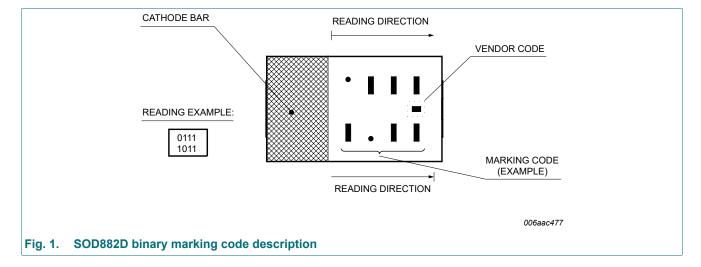
**Table 3. Ordering information** 

Type number	Package				
	Name	Description	Version		
PMEG4002ELD-Q	DFN1006D-2	leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.65 mm pitch; 1 mm x 0.6 mm x 0.4 mm body	SOD882D		

# 7. Marking

#### Table 4. Marking codes

Type number	Marking code
PMEG4002ELD-Q	1011



## 8. Limiting values

#### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_R$	reverse voltage			-	40	V
I <sub>F(AV)</sub>	average forward current	$\delta$ = 0.5; f = 20 kHz; square wave; $T_{amb} \le$ 120 °C	[1]	-	0.2	Α
		$\delta$ = 0.5; f = 20 kHz; square wave; $T_{sp} \le$ 140 °C		-	0.2	Α
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ ms}; \delta \le 0.25$		-	1	Α
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> = 8 ms; square wave		-	3	Α
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	[2]	-	340	mW
			[3]	-	660	mW
			[4]	-	1	W
Tj	junction temperature			-	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C

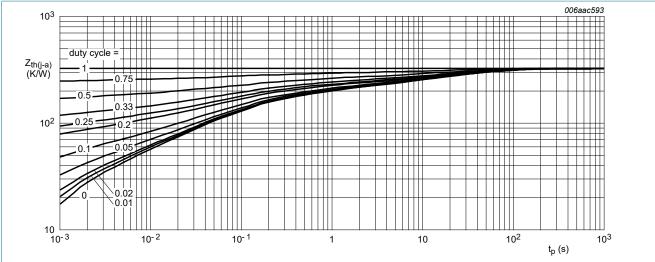
- Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm<sup>2</sup>.
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.

### 9. Thermal characteristics

#### **Table 6. Thermal characteristics**

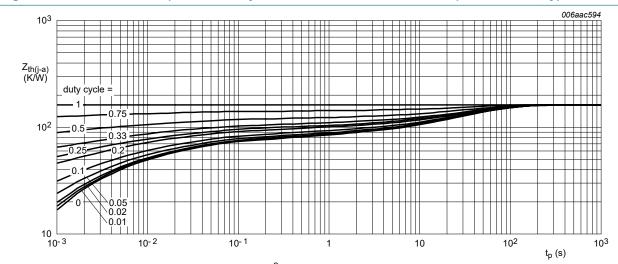
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	370	K/W
			[1] [3]	-	-	190	K/W
			[1] [4]	-	-	125	K/W
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		[5]	-	-	50	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P<sub>R</sub> are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm $^2$ .
- [4] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.
- [5] Soldering point of cathode tab.



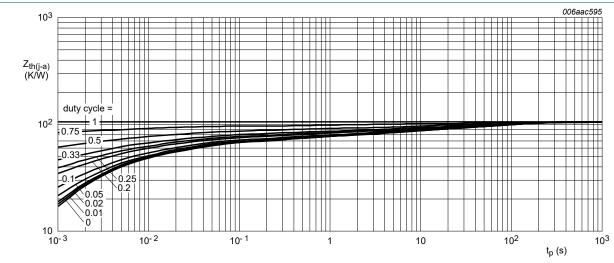
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>F</sub>	forward voltage	$I_F$ = 0.1 mA; pulsed; $t_p \le 300 \mu s$ ; δ ≤ 0.02; $T_{amb}$ = 25 °C	-	190	220	mV
		$I_F$ = 1 mA; pulsed; $t_p \le 300 \mu s$ ; $\delta \le 0.02$ ; $T_j$ = 25 °C	-	250	290	mV
		$I_F$ = 10 mA; pulsed; $t_p \le 300$ μs; $δ \le 0.02$ ; $T_{amb}$ = 25 °C	-	320	360	mV
		$I_F$ = 100 mA; $t_p \le 300$ μs; $δ \le 0.02$ ; $T_{amb}$ = 25 °C	-	450	500	mV
		$I_F$ = 200 mA; $t_p \le 300$ μs; $δ \le 0.02$ ; $T_{amb}$ = 25 °C	-	540	600	mV
I <sub>R</sub>	reverse current	V <sub>R</sub> = 25 V; T <sub>amb</sub> = 25 °C	-	0.3	0.5	μΑ
		V <sub>R</sub> = 40 V; T <sub>amb</sub> = 25 °C	-	0.6	10	μΑ
C <sub>d</sub>	diode capacitance	V <sub>R</sub> = 1 V; f = 1 MHz; T <sub>amb</sub> = 25 °C	-	14	20	pF
t <sub>rr</sub>	reverse recovery time	$I_F$ = 10 mA; $I_R$ = 10 mA; $I_{R(meas)}$ = 1 mA; $I_L$ = 100 Ω; $I_J$ = 25 °C	-	4	-	ns

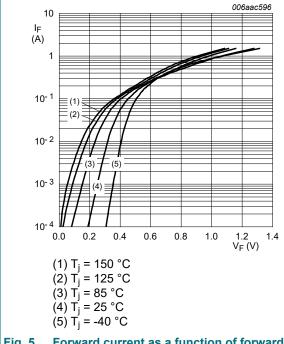


Fig. 5. Forward current as a function of forward voltage; typical values

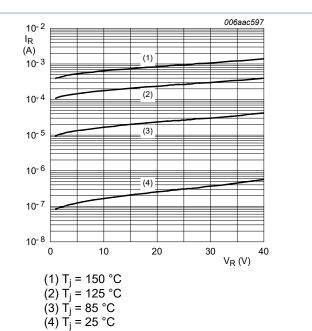


Fig. 6. Reverse current as a function of reverse voltage; typical values

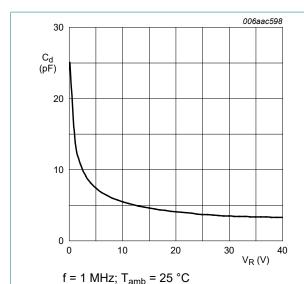
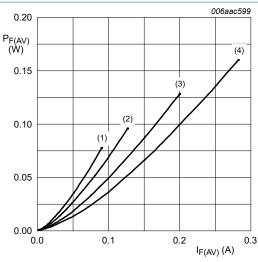
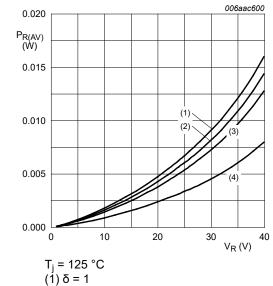


Fig. 7. Diode capacitance as a function of reverse voltage; typical values



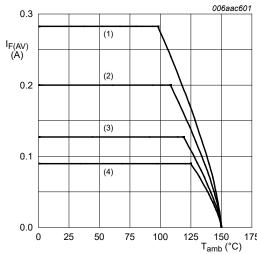
T<sub>i</sub> = 150 °C  $(1) \delta = 0.1$  $(2) \delta = 0.2$  $(3) \delta = 0.5$  $(4) \delta = 1$ 

Average forward power dissipation as a function of average forward current; typical values



 $(2) \delta = 0.9$  $(3) \delta = 0.8$  $(4) \delta = 0.5$ 

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint T<sub>i</sub> = 150 °C

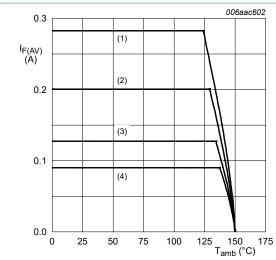
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 10. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm<sup>2</sup>

 $T_i = 150 \, ^{\circ}C$ 

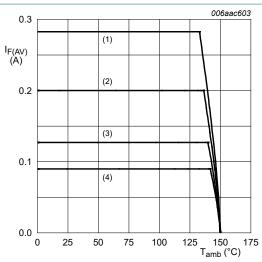
 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint

T<sub>i</sub> = 150 °C

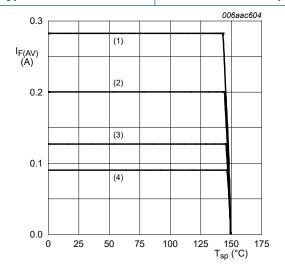
 $(1) \delta = 1; DC$ 

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 12. Average forward current as a function of ambient temperature; typical values



T<sub>i</sub> = 150 °C

 $(1) \delta = 1$ ; DC

(2)  $\delta = 0.5$ ; f = 20 kHz

(3)  $\delta = 0.2$ ; f = 20 kHz

(4)  $\delta = 0.1$ ; f = 20 kHz

Fig. 13. Average forward current as a function of solder point temperature; typical values

### 11. Test information

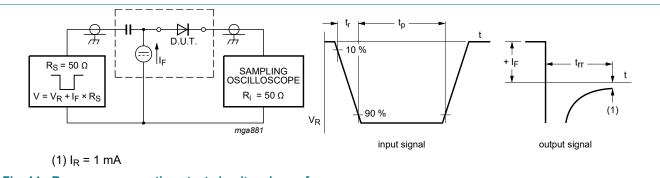


Fig. 14. Reverse recovery time: test circuit and waveforms

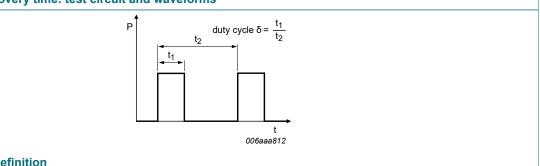


Fig. 15. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

 $I_{F(AV)} = I_M \times \delta$  with  $I_M$  defined as peak current

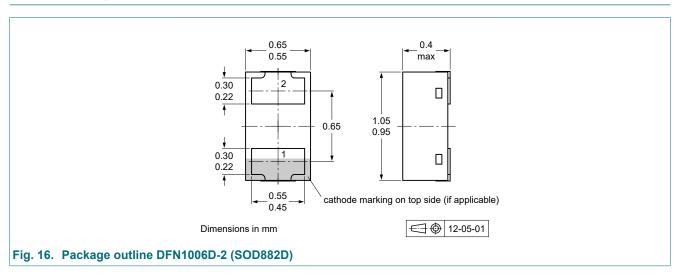
 $I_{RMS} = I_{F(AV)}$  at DC

 $I_{RMS} = I_{M} \times \sqrt{\delta}$  with  $I_{RMS}$  defined as RMS current

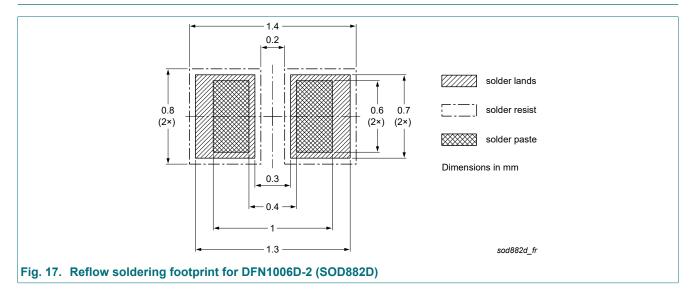
### **Quality information**

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

# 12. Package outline



# 13. Soldering



# 14. Revision history

#### **Table 8. Revision history**

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4002ELD-Q v.1	20240708	Product data sheet	-	-

## 15. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- Please consult the most recently issued document before initiating or completing a design.
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For more information, please visit: http://www.nexperia.com For sales office addresses, please send an email to: salesaddresses@nexperia.com Date of release: 8 July 2024

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